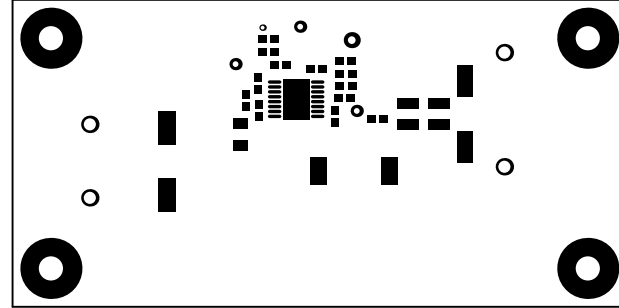
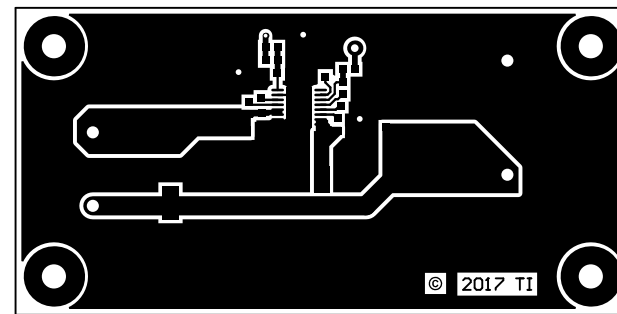


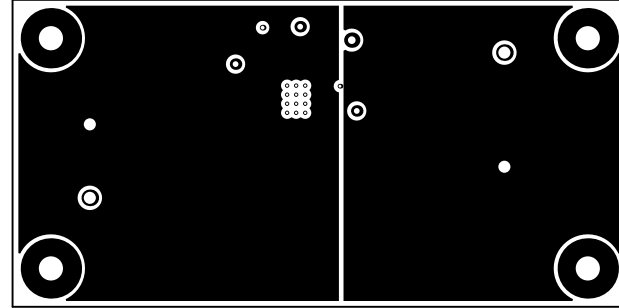
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20999	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Overlay			
PLOT NAME = Top Overlay	GENERATED : 11/30/2017 5:40:47 PM	TEXAS INSTRUMENTS	



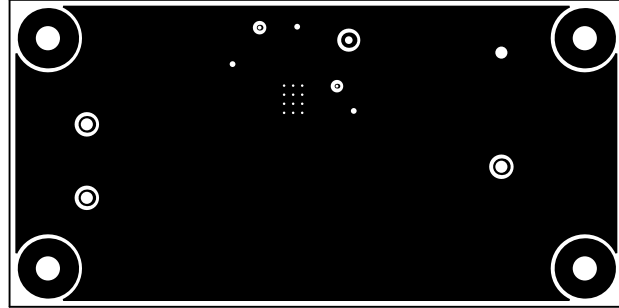
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20999	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Solder			
PLOT NAME = Top Solder Mask	GENERATED : 11/30/2017 5:40:48 PM	TEXAS INSTRUMENTS	



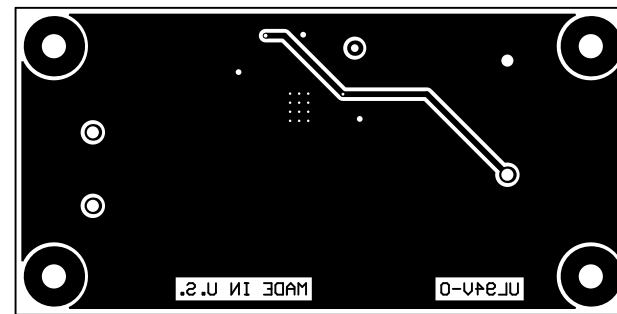
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20999	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Top Layer			
PLOT NAME = Top Layer	GENERATED : 11/30/2017 5:40:49 PM	TEXAS INSTRUMENTS	



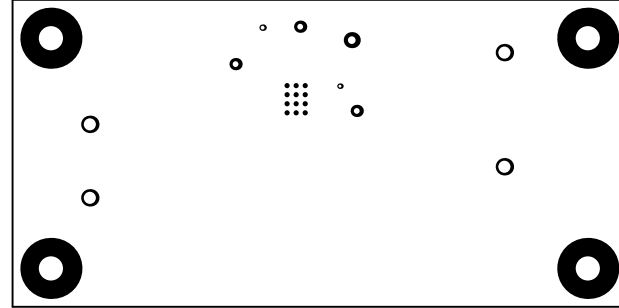
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20999	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 1	GENERATED : 11/30/2017 5:40:50 PM	TEXAS INSTRUMENTS	



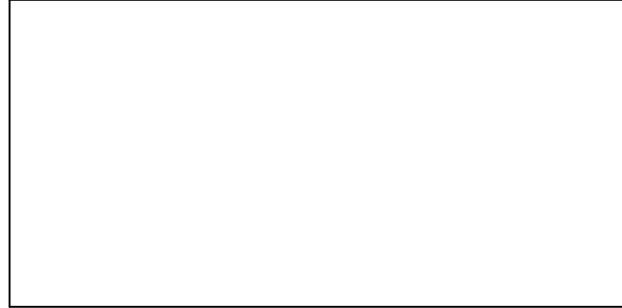
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20999	REV: B	SUN REV: Not In VersionControl
LAYER NAME =			
PLOT NAME = Signal Layer 2	GENERATED : 11/30/2017 5:40:50 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20999	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Layer			
PLOT NAME = Bottom Layer	GENERATED : 11/30/2017 5:40:51 PM	TEXAS INSTRUMENTS	

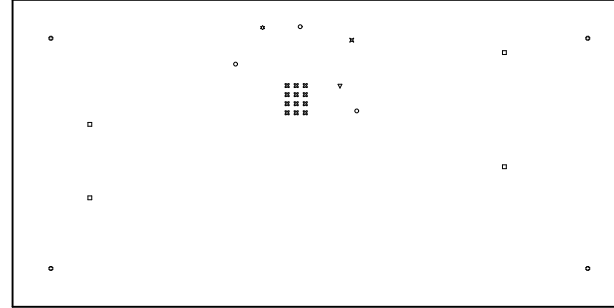


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20999	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder			
PLOT NAME = Bottom Solder Mask	GENERATED : 11/30/2017 5:40:52 PM	TEXAS INSTRUMENTS	



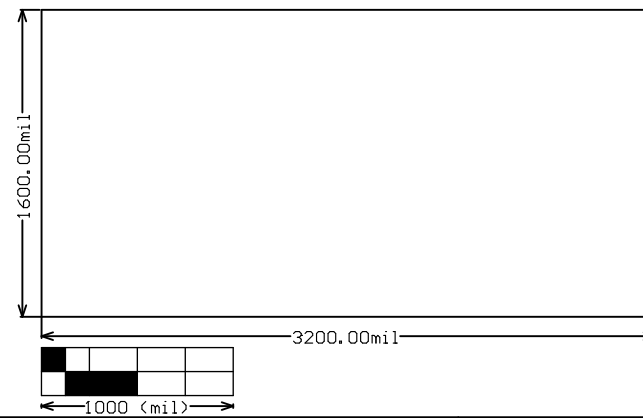
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20999	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Bottom Overlay			
PLOT NAME = Bottom Overlay	GENERATED : 11/30/2017 5:40:53 PM	TEXAS INSTRUMENTS	





Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
⊗	12	13.00mil (0.330mm)	PTH	Round	Top Layer - Bottom Layer	
▽	1	15.00mil (0.381mm)	PTH	Round	Top Layer - Bottom Layer	
☆	1	20.00mil (0.508mm)	PTH	Round	Top Layer - Bottom Layer	
○	3	30.00mil (0.762mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	1	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
□	4	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
⊗	4	125.98mil (3.200mm)	PTH	Round	Top Layer - Bottom Layer	
26 Total						

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20999	REV: B	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing			
PLOT NAME = Drill Drawing	GENERATED : 11/30/2017 5:40:54 PM	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: PMP20999	REV: B	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions			
PLOT NAME = Board Dimensions	GENERATED : 11/30/2017 5:40:55 PM	TEXAS INSTRUMENTS	

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